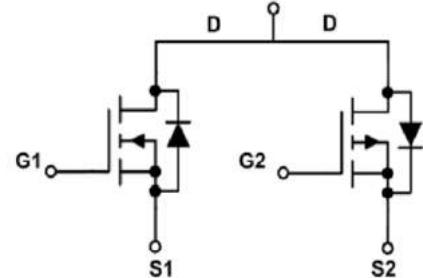




■ PRODUCT CHARACTERISTICS

N-Channel	P-Channel
$BV_{DSS} = 40V$	$BV_{DSS} = -40V$
$R_{DS(on)}(\text{Typ@VGS= } 10V) < 17m\Omega$	$R_{DS(on)}(\text{Typ@VGS= } -10V) < 29m\Omega$
$R_{DS(on)}(\text{Typ@VGS= } 4.5V) < 22m\Omega$	$R_{DS(on)}(\text{Typ@VGS= } -4.5V) < 34m\Omega$

Symbol



■ APPLICATIONS

- Motor Drive
- DC-DC Converter

■ FEATURES

- Advanced trench cell design
- Super trench
- Low thermal resistance

■ Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise specified)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	40	-40	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current	$T_c=25^\circ C$	I_D	28	A
	$T_c=100^\circ C$		19.8	A
Pulsed Drain Current ^(Note 1)	I_{DM}	70	-60	A
Maximum Power Dissipation	$T_c=25^\circ C$	P_D	35	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150		°C

■ THERMAL DATA

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	3.6	°C/W
--	-----------------	-----	------

■ N-Channel Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1.0	1.4	2.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=15\text{A}$	-	17	22	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=10\text{A}$	-	22	30	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=15\text{A}$	-	7	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	964	-	PF
Output Capacitance	C_{oss}		-	109	-	PF
Reverse Transfer Capacitance	C_{rss}		-	96	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=20\text{V}, \text{R}_L=2.5\Omega$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=3\Omega$	-	5.5	-	nS
Turn-on Rise Time	t_r		-	14	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	24	-	nS
Turn-Off Fall Time	t_f		-	5	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=20\text{V}, \text{I}_D=15\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	22.9	-	nC
Gate-Source Charge	Q_{gs}		-	3.5	-	nC
Gate-Drain Charge	Q_{gd}		-	5.3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=15\text{A}$	-	-	1.2	V
Diode Forward Current ^(Note 2)	I_s		-	-	28	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $\text{T}_j=25^\circ\text{C}, \text{VDD}=20\text{V}, \text{VG}=10\text{V}, \text{L}=0.5\text{mH}, \text{R}_g=25\Omega$

■ N-CHANNEL TEST CIRCUITS AND WAVEFORMS

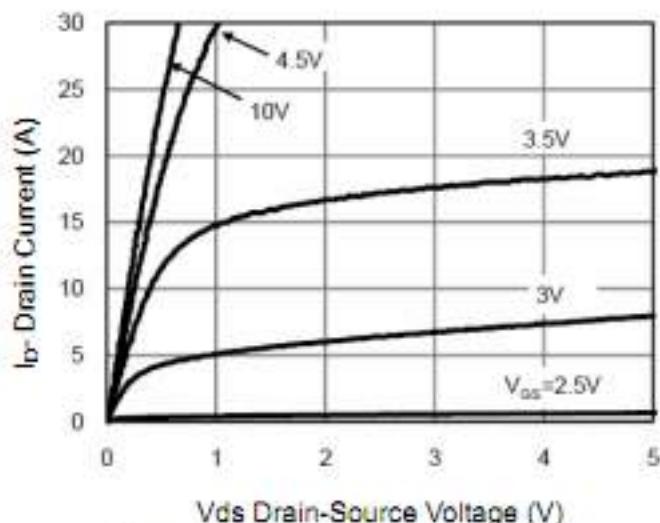


Figure 1 Output Characteristics

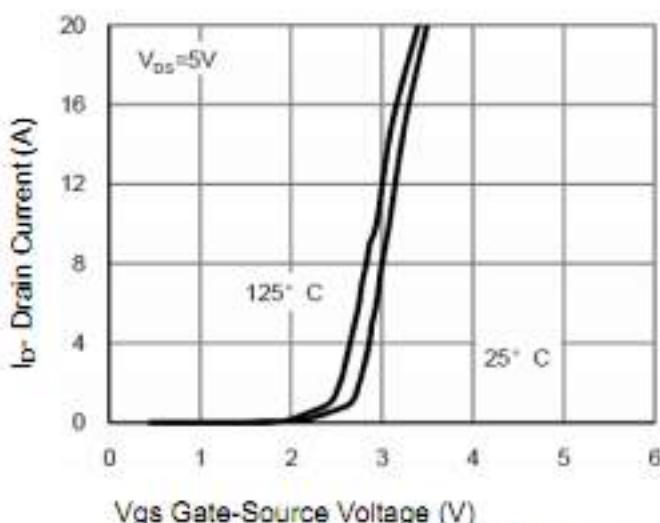


Figure 2 Transfer Characteristics

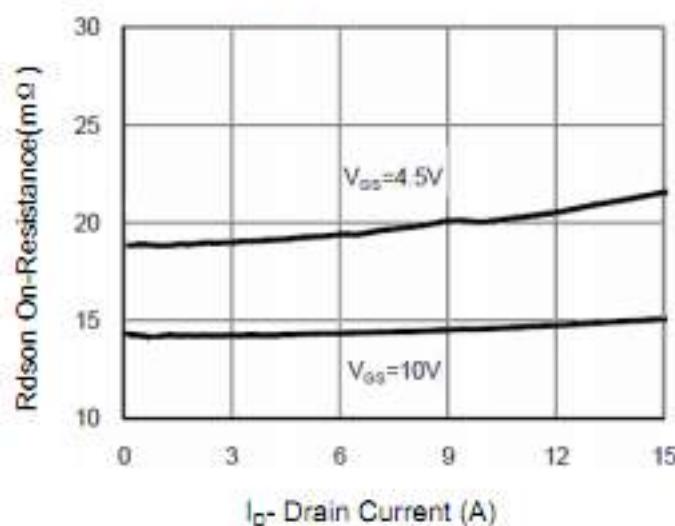


Figure 3 Drain-Source On-Resistance

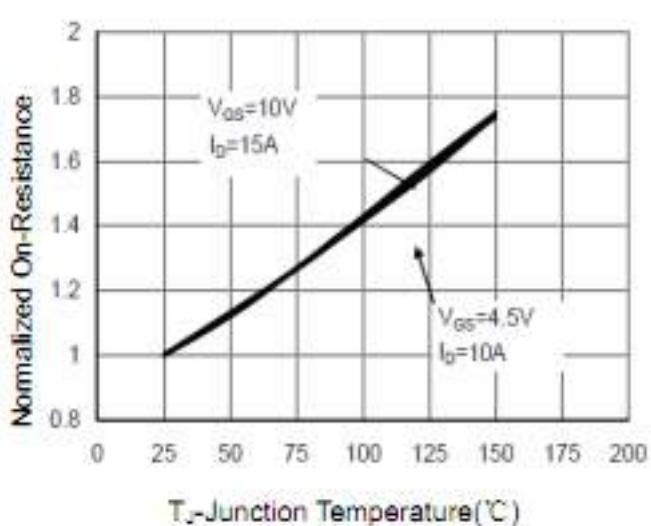


Figure 4 Drain-Source On-Resistance

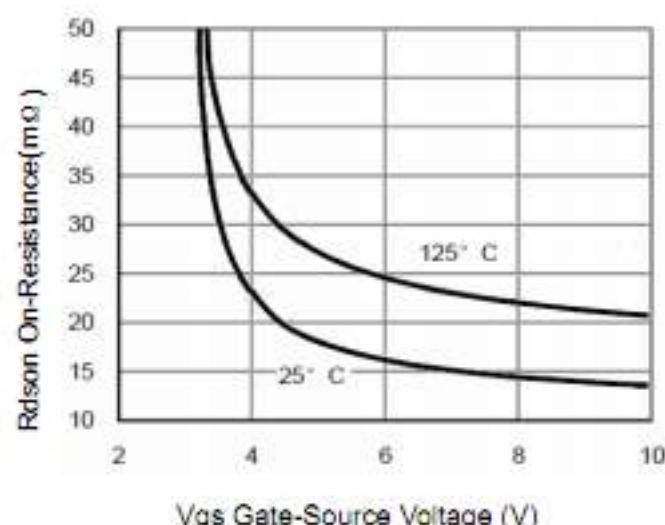


Figure 5 Rdson vs Vgs

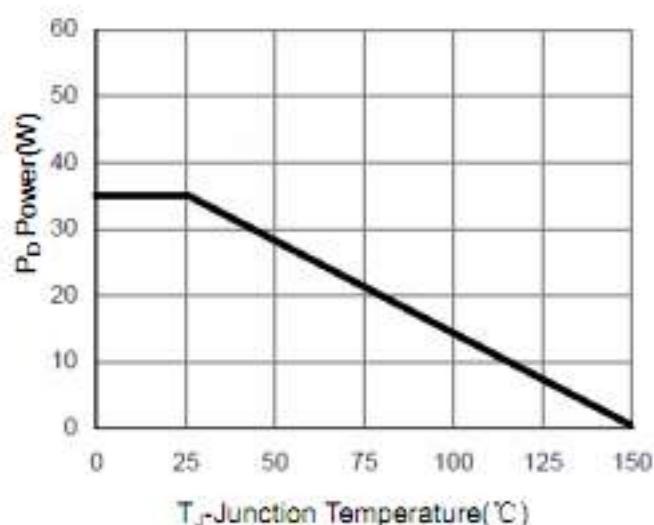


Figure 6 Power Dissipation

■ N-CHANNEL TEST CIRCUITS AND WAVEFORMS(Cont.)

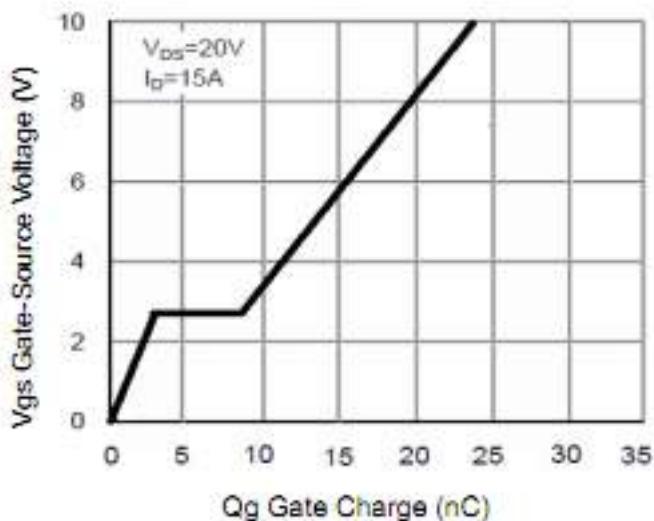


Figure 7 Gate Charge

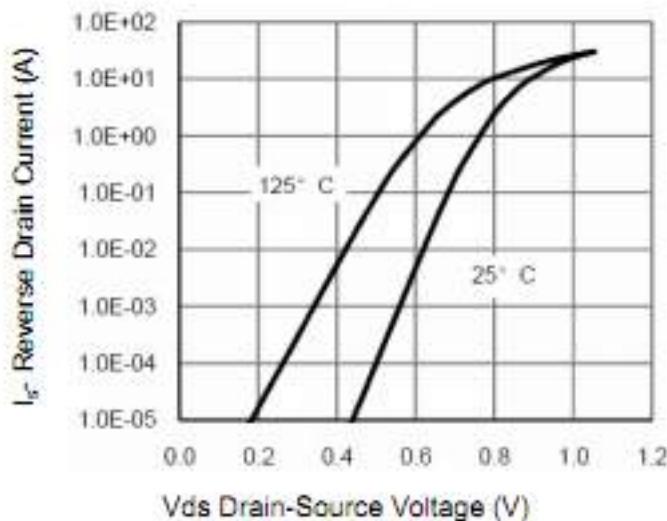


Figure 8 Source- Drain Diode Forward

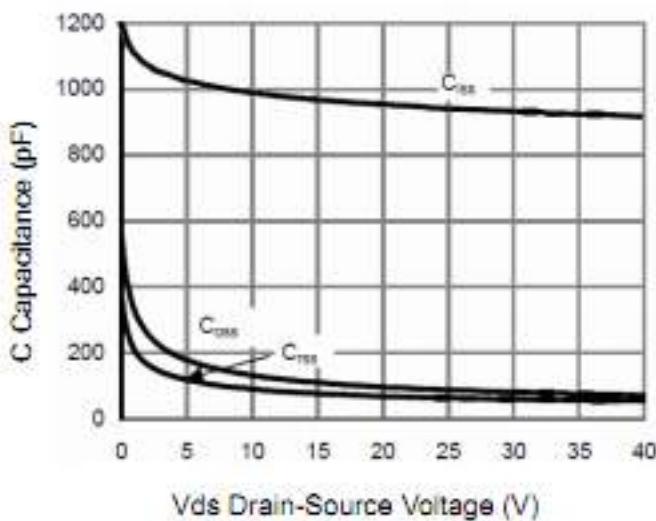


Figure 9 Capacitance vs Vds

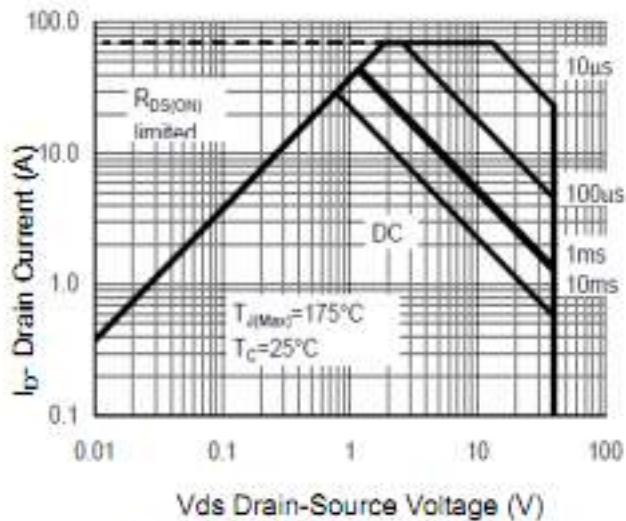


Figure 10 Safe Operation Area

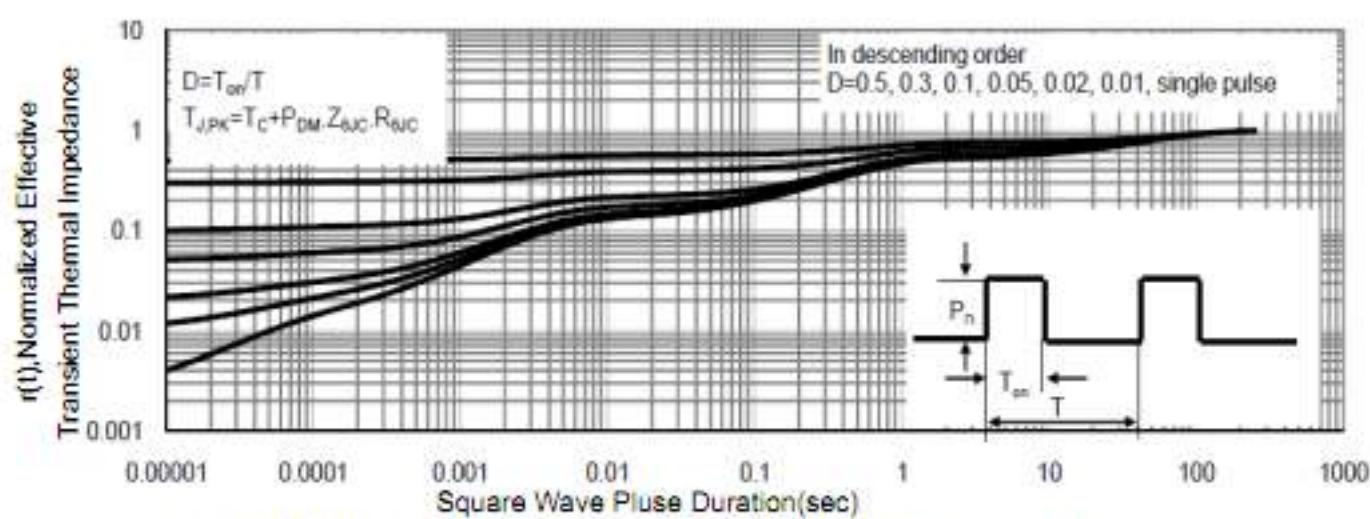


Figure 11 Normalized Maximum Transient Thermal Impedance

■ P-Channel Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.5	-2.0	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-7\text{A}$	-	29	35	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-4\text{A}$	-	34	45	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-7\text{A}$	20	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	964	-	PF
Output Capacitance	C_{oss}		-	109	-	PF
Reverse Transfer Capacitance	C_{rss}		-	96	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-20\text{V}, R_{\text{L}}=2.3\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=6\Omega$	-	5.5	-	nS
Turn-on Rise Time	t_r		-	14	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	24	-	nS
Turn-Off Fall Time	t_f		-	12	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-7\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	22.9	-	nC
Gate-Source Charge	Q_{gs}		-	3.5	-	nC
Gate-Drain Charge	Q_{gd}		-	5.3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-10\text{A}$	-	-	1.2	V

■ P-CHANNEL TEST CIRCUITS AND WAVEFORMS

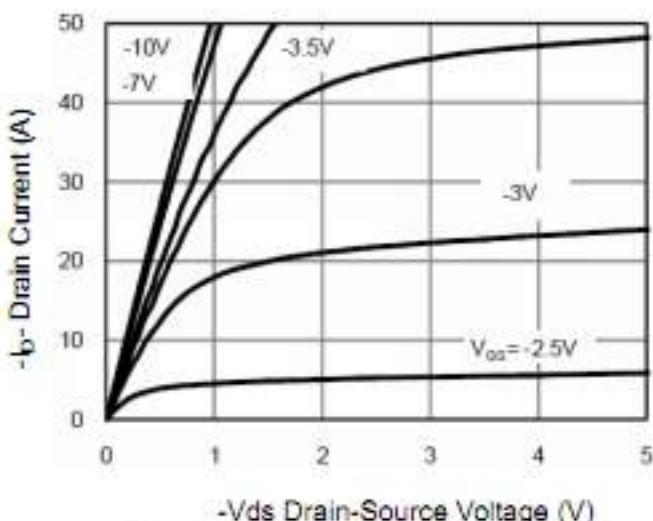


Figure 1 Output Characteristics

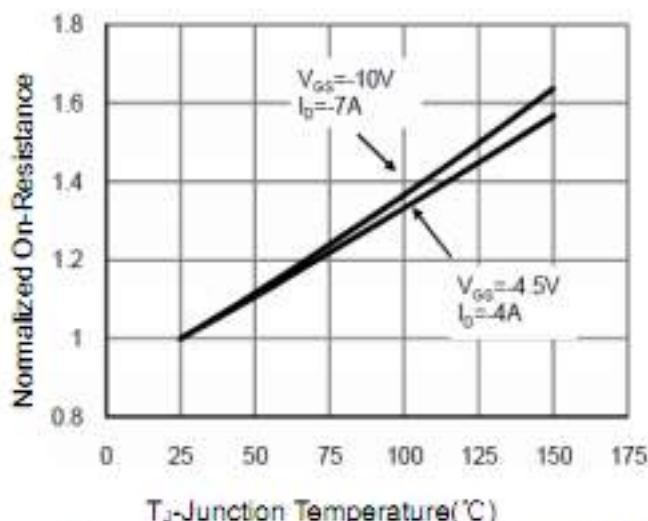


Figure 4 Rdson-Junction Temperature

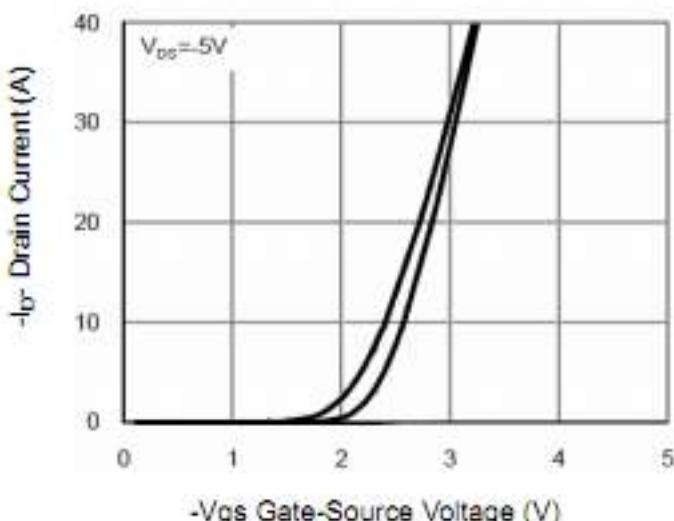


Figure 2 Transfer Characteristics

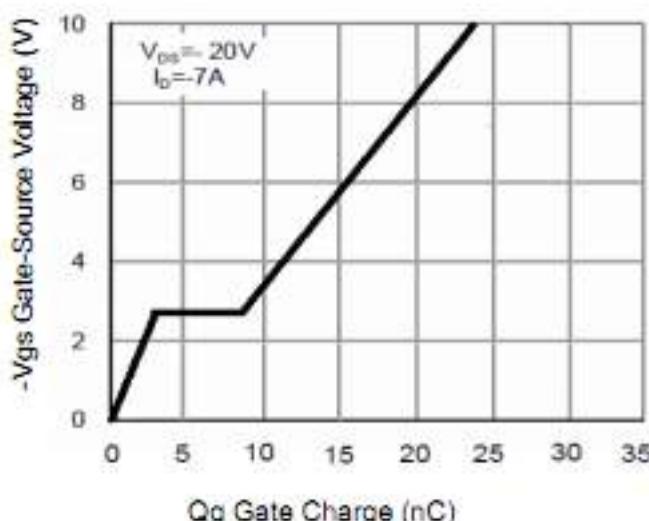


Figure 5 Gate Charge

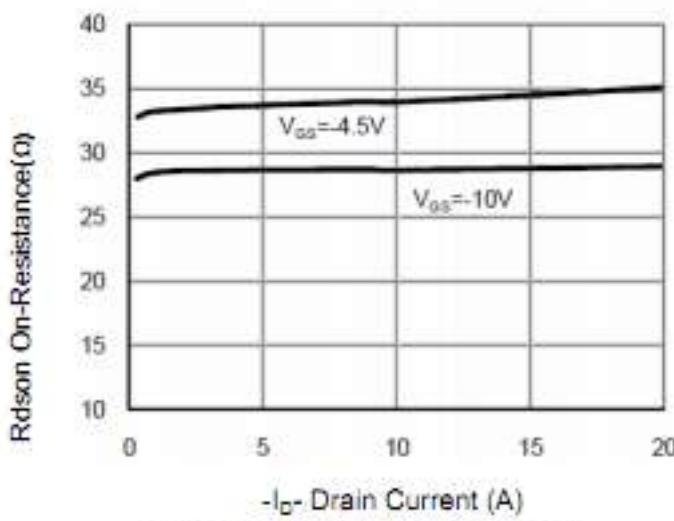


Figure 3 Rdson-Drain Current

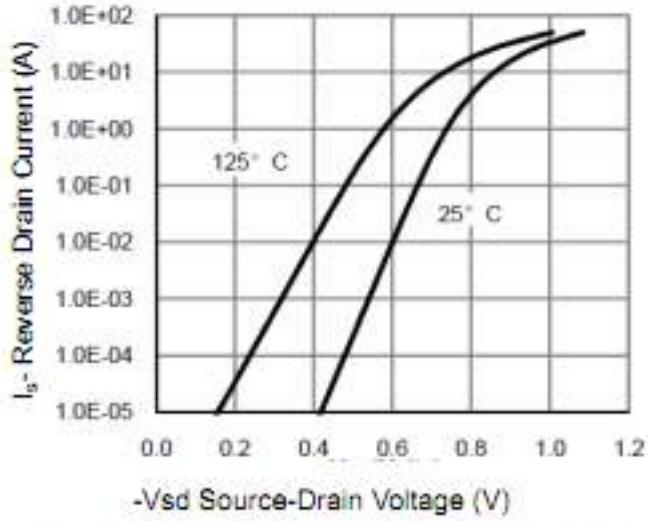


Figure 6 Source-Drain Diode Forward

■ P-CHANNEL TEST CIRCUITS AND WAVEFORMS(Cont.)

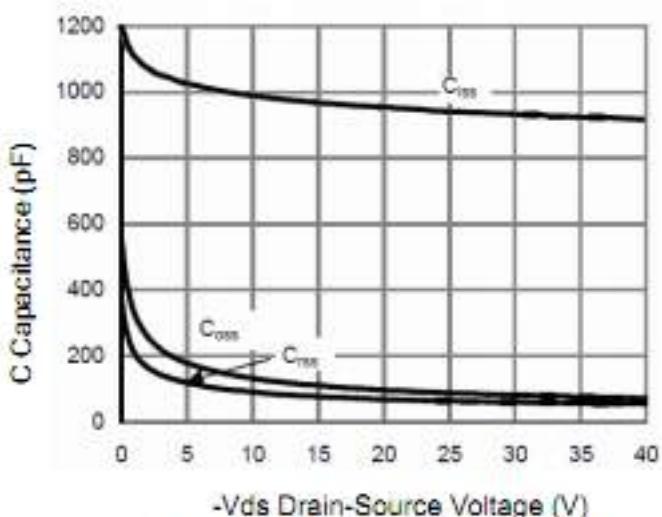


Figure 7 Capacitance vs Vds

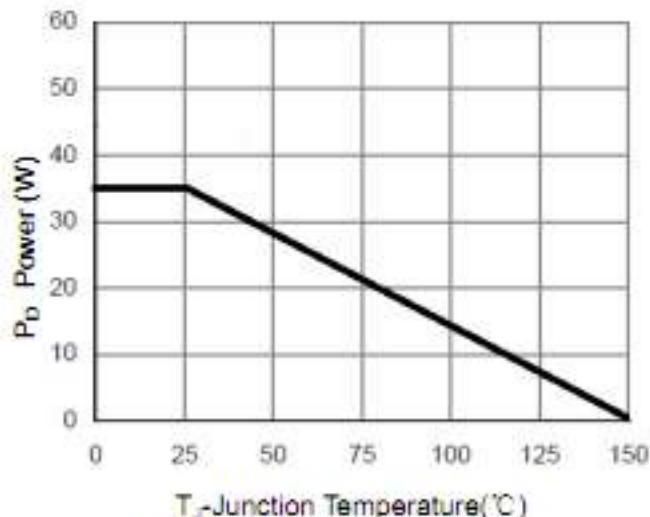


Figure 9 Power Dissipation

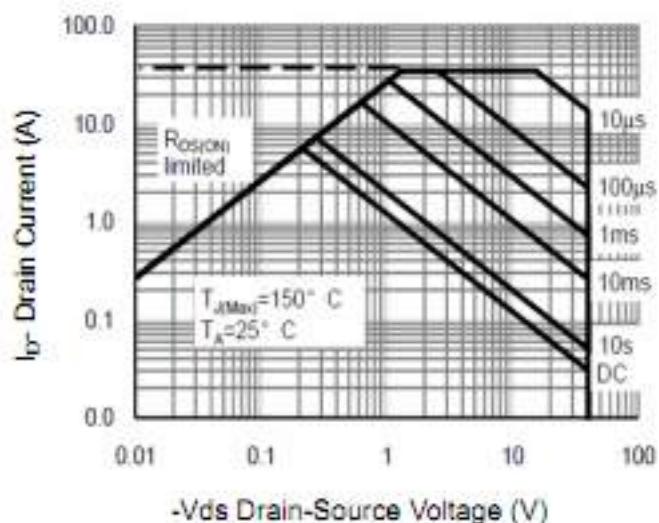


Figure 8 Safe Operation Area

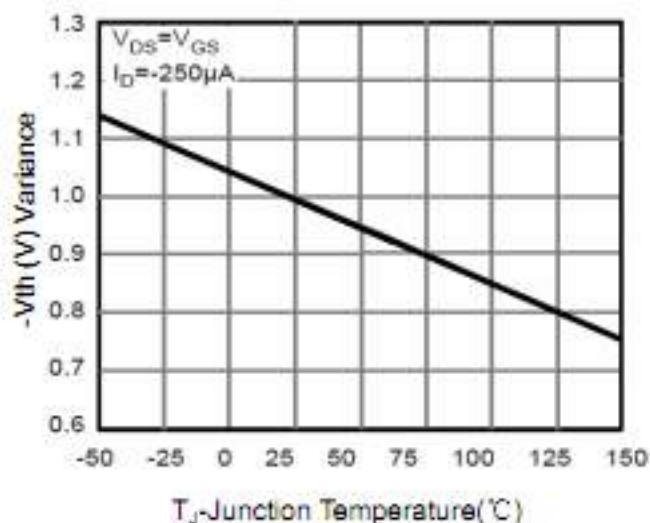
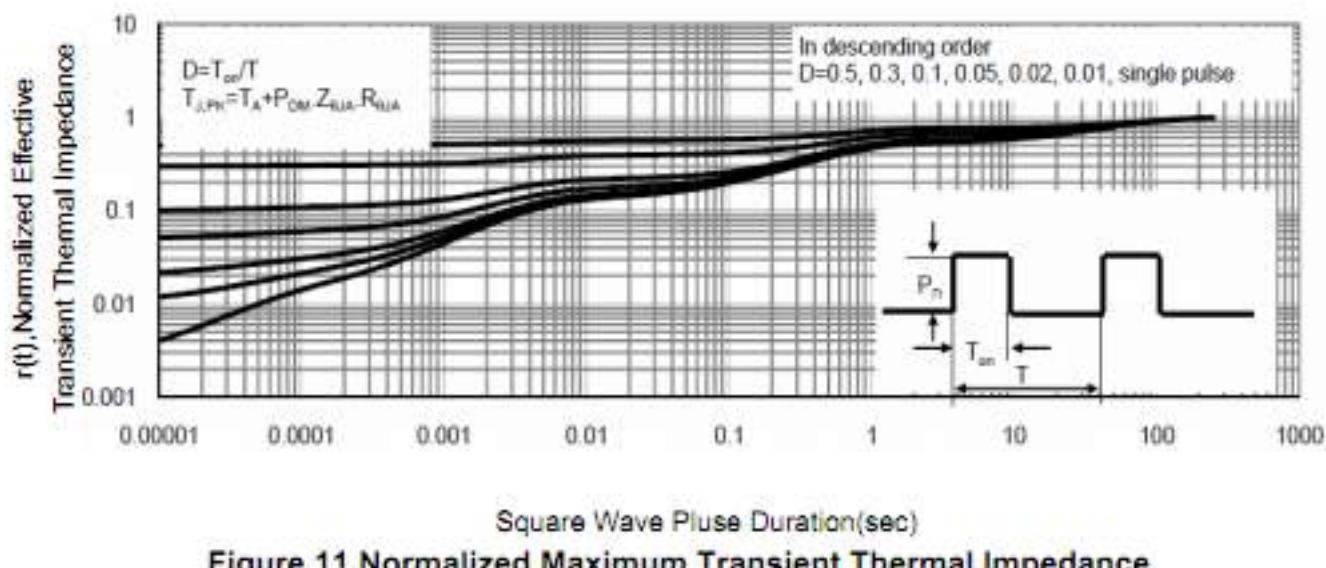
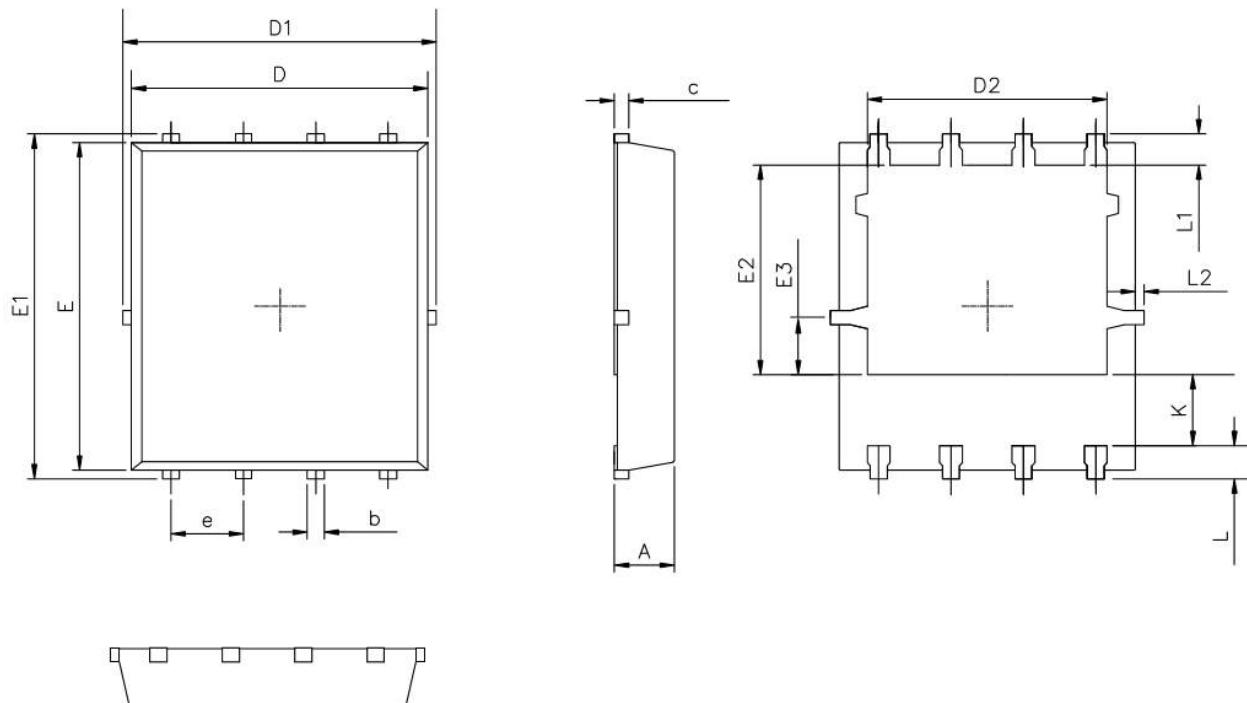
Figure 10 $V_{GS(th)}$ vs Junction Temperature

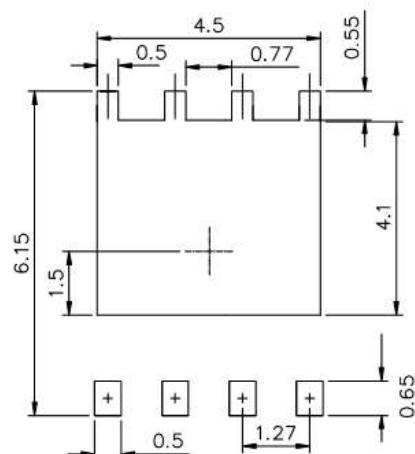
Figure 11 Normalized Maximum Transient Thermal Impedance



■ PDFN5060-8L Package Mechanical Data



RECOMMENDED LAND PATTERN



UNIT:mm

	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.35	0.50
c	0.10	0.20	0.30
D	4.80	5.00	5.30
D1	4.90	5.10	5.50
D2	3.92	4.02	4.20
E	5.65	5.75	5.85
E1	5.90	6.05	6.20
E2	3.325	3.525	3.775
E3	0.80	0.90	1.00
e		1.27	
L	0.40	0.55	0.70
L1		0.65	
L2	0.00		0.15
K	1.00	1.30	1.50

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